

IGBT

Features

- 650V,75A
- V_{CE(sat)(typ.)}=1.45V@V_{GE}=15V,I_C=75A
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms
- Square RBSOA

General Description

JIAEN Trench IGBTs offer lower losses and higher energy

efficiency for application such as UPS, Induction converters,

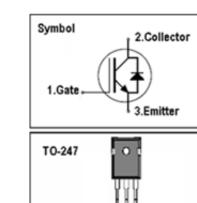
Uninterruptible power supplies and other soft switching applications.

Absolute Maximum Ratings

Symbol	Parameter	Value	Units	
Vces	Collector-Emitter Voltage	650	V	
Vges	Gate-Emitter Voltage	<u>+</u> 30	V	
	Continuous Collector Current (Tc=25 $^\circ\!\mathrm{C}$)	150	А	
lc	Continuous Collector Current (Tc=100 $^\circ\!\!\!\mathrm{C}$)	75	A	
Ісм	Pulsed Collector Current (Note 1)	225	A	
IF	Diode Continuous Forward Current ($T_C {=} 100~^\circ {\rm C}$)	75	A	
Ifm	Diode Maximum Forward Current (Note 1)	225	A	
D-	Maximum Power Dissipation (Tc=25 $^\circ\!\!\!\mathrm{C}$)	405	W	
PD	Maximum Power Dissipation ($T_C=100^\circ\!\!\mathrm{C}$)	203	W	
TJ	Operating Junction Temperature Range	-55 to +175	°C	
Тѕтс	Storage Temperature Range	-55 to +175	°C	

Thermal Characteristics

Symbol	Parameter	Max.	Units
Rth j-c	Thermal Resistance, Junction to case for IGBT	0.37	°C/W
Rth j-c	Thermal Resistance, Junction to case for Diode	0.8	°C/ W
R _{th j-a}	Thermal Resistance, Junction to Ambient	40	°C/W



GCE



Electrical Characteristics ($T_c=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV _{CES}	Collector-Emitter Breakdown Voltage	V _{GE} = 0V, I _C = 250uA	650	-	-	V
I _{CES}	Collector-Emitter Leakage Current	V _{CE} = 650V, V _{GE} = 0V	-	-	100	uA
I _{GES}	Gate Leakage Current, Forward	V_{GE} =±20V, V_{CE} = 0V	-	-	±100	nA
V _{GE(th)}	Gate Threshold Voltage	$V_{GE} = V_{CE}, I_C = 500 \text{uA}$	3.3	-	5.7	V
V _{CE(sat)}	Collector-Emitter Saturation Voltage	V _{GE} =15V, I _C = 75A	-	1.45	1.95	V
Qg	Total Gate Charge	V _{cc} =480V	-	215		nC
Qge	Gate-Emitter Charge	V _{GE} =15V	-	50.9		nC
Q _{gc}	Gate-Collector Charge	Ic=75A	-	83.8		nC
t d(on)	Turn-on Delay Time		-	89	-	ns
t r	Turn-on Rise Time	Vcc=400V	-	128	-	ns
t d(off)	Turn-off Delay Time	$V_{GE}=15V$ $I_{C}=75A$ $R_{G}=15\Omega$ Inductive Load $T_{C}=25 \ ^{\circ}C$	-	377	-	ns
t f	Turn-off Fall Time		-	110	-	ns
Eon	Turn-on Switching Loss		-	3.7	-	mJ
Eoff	Turn-off Switching Loss		-	2.7	-	mJ
Ets	Total Switching Loss		-	6.4	-	mJ
Cies	Input Capacitance	V _{CE} =25V	-	7244	-	рF
Coes	Output Capacitance	V _{GE} =0V	-	215	-	pF
Cres	Reverse Transfer Capacitance	f = 1MHz	-	29	-	pF

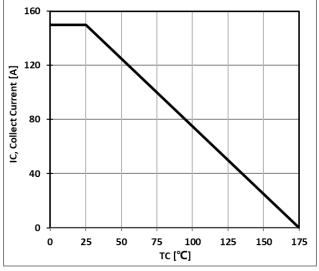
Electrical Characteristics of Diode (Tc=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V _F	Diode Forward Voltage	I _F = 75A	-	1.5	3.0	V
trr	Diode Reverse Recovery Time	V _{CE} = 400V	-	148		ns
Irr	Diode peak Reverse Recovery Current	I _F = 75A	-	25		Α
Q _{r r}	Diode Reverse Recovery Charge	dif/dt= 600A/ns	-	2375		nC

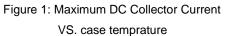
Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature





Typical Performance Characteristics



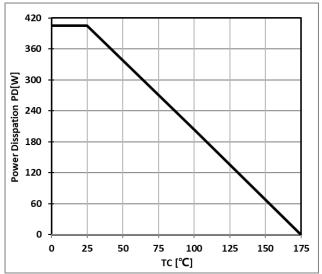
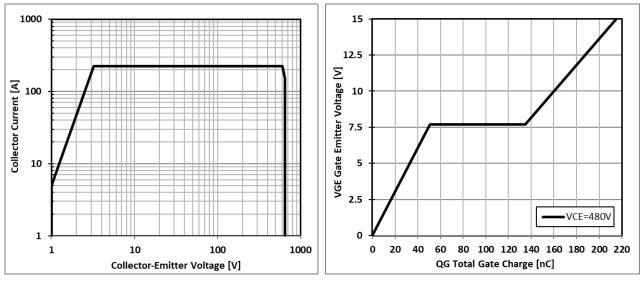


Figure 2: Power Dissipation VS. Case Temperature



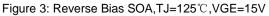
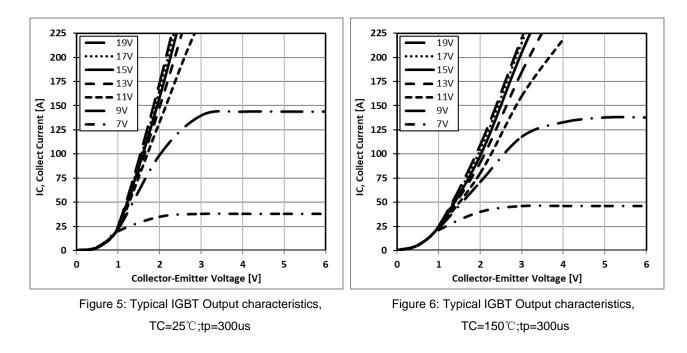
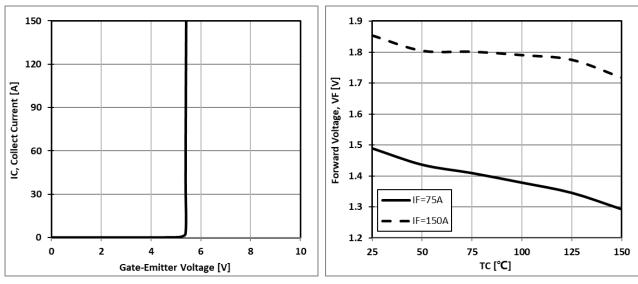
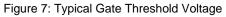


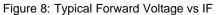
Figure 4: Typical Gate charge VS. VGE,IC=75A













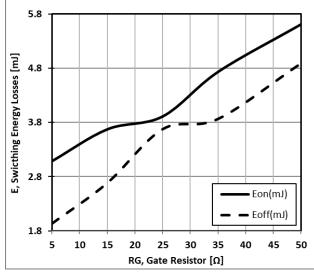


Figure 9: Typical Energy Loss VS. RG, TC=25℃, L=200uH,VCE=400V,VGE=15V,IC=75A

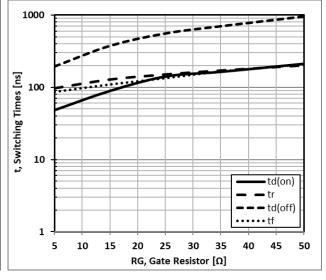
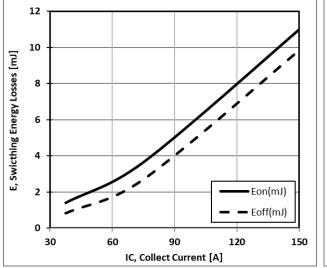
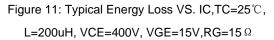
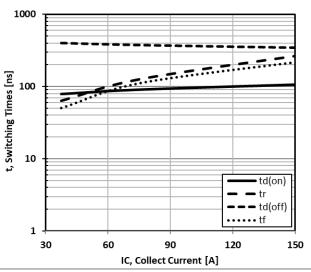
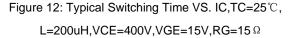


Figure 10: Typical Switching Time VS. RG, TC=25℃, L=200uH,VCE=400V,VGE=15V,IC=75A

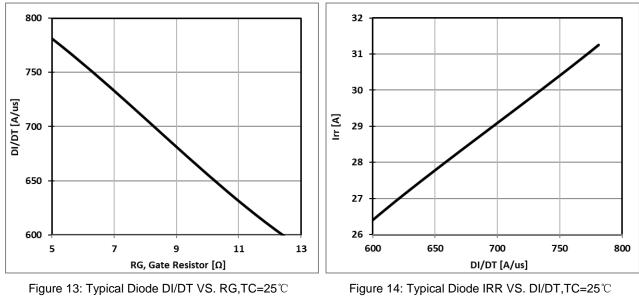




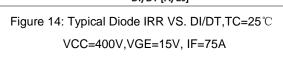


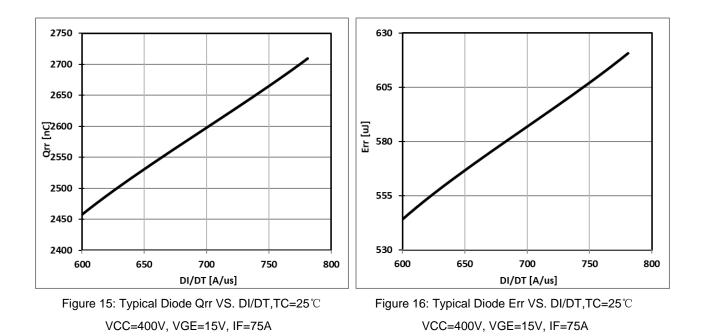




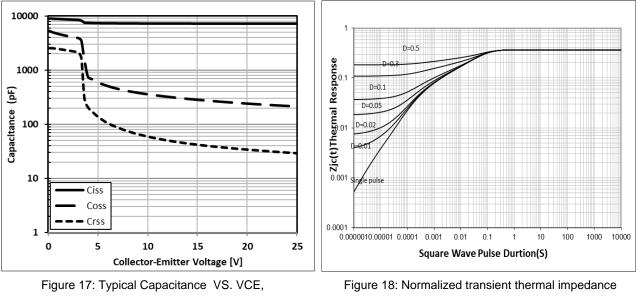










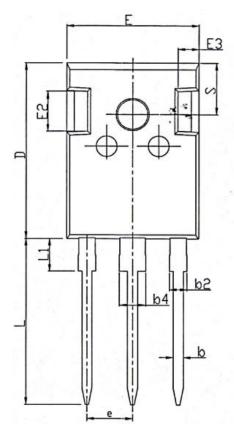


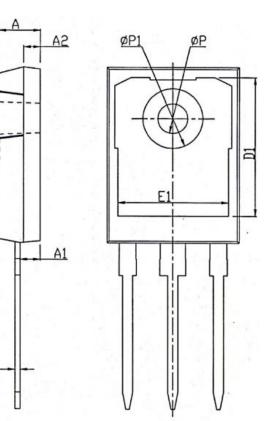






TO-247 PACKAGE OUTLINE





	mm			
SYMBOL	MIN	TYP	MAX	
А	4.80	5.00	5.20	
A1	2.21	2.41	2.61	
A2	1.85	2.00	2.15	
b	1.11	1.21	1.36	
b2	1.91	2.01	2.21	
b4	2.91	3.01	3.21	
С	0.51	0.61	0.75	
D	20.70	21.00	21.30	
D1	16.25	16.55	16.85	
E	15.50	15.80	16.10	
E1	13.00	13.30	13.60	
E2	4.80	5.00	5.20	
E3	2.30	2.50	2.70	
е	5.44BSC			
L	19.62	19.92	20.22	
L1	-	-	4.30	
ØP	3.40	3.60	3.80	
ØP1	-	-	7.30	
S	S 6.15BSC			

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